

PATENT ASSIGNMENT

Electronic Version v1.1
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| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | | | | | |
|--|---|---------------|---|---------------------|------------------------------|-------------------|------------|---------------|--------------|----------------|------------|--------------|------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT | | | | | | | | | | | | |
| CONVEYING PARTY DATA | | | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Takahiro Ibe</td> <td>09/04/2012</td> </tr> <tr> <td>Tomoya Aoyama</td> <td>09/05/2012</td> </tr> <tr> <td>Rena Tsuruoka</td> <td>09/11/2012</td> </tr> <tr> <td>Satoshi Inoue</td> <td>09/10/2012</td> </tr> <tr> <td>Tohru Sonoda</td> <td>09/10/2012</td> </tr> </tbody> </table> | | Name | Execution Date | Takahiro Ibe | 09/04/2012 | Tomoya Aoyama | 09/05/2012 | Rena Tsuruoka | 09/11/2012 | Satoshi Inoue | 09/10/2012 | Tohru Sonoda | 09/10/2012 |
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| RECEIVING PARTY DATA | | | | | | | | | | | | | |
| <table border="1"> <tr> <td>Name:</td> <td>Semiconductor Energy Laboratory Co., Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>398 Hase</td> </tr> <tr> <td>Internal Address:</td> <td>Atsugi-shi</td> </tr> <tr> <td>City:</td> <td>Kanagawa-ken</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>243-0036</td> </tr> </table> | | Name: | Semiconductor Energy Laboratory Co., Ltd. | Street Address: | 398 Hase | Internal Address: | Atsugi-shi | City: | Kanagawa-ken | State/Country: | JAPAN | Postal Code: | 243-0036 |
| Name: | Semiconductor Energy Laboratory Co., Ltd. | | | | | | | | | | | | |
| Street Address: | 398 Hase | | | | | | | | | | | | |
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| State/Country: | JAPAN | | | | | | | | | | | | |
| Postal Code: | 243-0036 | | | | | | | | | | | | |
| <table border="1"> <tr> <td>Name:</td> <td>Sharp Kabushiki Kaisha</td> </tr> <tr> <td>Street Address:</td> <td>22-22, Nagaike-cho, Abeno-ku</td> </tr> <tr> <td>Internal Address:</td> <td>Osaka-shi</td> </tr> <tr> <td>City:</td> <td>Osaka</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>545-8522</td> </tr> </table> | | Name: | Sharp Kabushiki Kaisha | Street Address: | 22-22, Nagaike-cho, Abeno-ku | Internal Address: | Osaka-shi | City: | Osaka | State/Country: | JAPAN | Postal Code: | 545-8522 |
| Name: | Sharp Kabushiki Kaisha | | | | | | | | | | | | |
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| PROPERTY NUMBERS Total: 1 | | | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13635227</td> </tr> </tbody> </table> | | Property Type | Number | Application Number: | 13635227 | | | | | | | | |
| Property Type | Number | | | | | | | | | | | | |
| Application Number: | 13635227 | | | | | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | | | | | |
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CH \$40.00 13635227

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Address Line 4: CHICAGO, ILLINOIS 60606

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| ATTORNEY DOCKET NUMBER: | (0553-1049) |
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|--------------------|----------------|
| NAME OF SUBMITTER: | Mark J. Murphy |
|--------------------|----------------|

Total Attachments: 6
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ASSIGNMENT

Identity Of The Patent Application. I am the inventor (or one joint inventor) of a patent application that I am assigning. The patent application I am assigning is entitled

DEPOSITION METHOD AND METHOD FOR MANUFACTURING DEPOSITION SUBSTRATE

which I executed herewith. If the patent application has already been filed, it received serial number

_____ and bears a filing date of _____.

The Assignee and The Assignment. I assign my patent rights to Semiconductor Energy Laboratory Co., Ltd., a corporation organized according to the laws of Japan, having a place of business at 398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan and Sharp Kabushiki Kaisha, a corporation organized according to the laws of Japan, having a place of business at 22-22, Nagaike-cho, Abeno-ku, Osaka-shi, Osaka 545-8522 Japan (hereinafter "the Assignee"). The rights I assign are my entire right, title and interest in the invention or improvements disclosed in the patent application and any and all other applications for United States Letters Patent which I may file, either solely or jointly with others, on the invention or improvements, including all continuations, divisionals, and continuations-in-part, and in any and all United States Letters Patent which may be obtained on any of said applications, and in any reissue or extension thereof. I also assign to the Assignee all priority rights under the International Convention. I agree to execute, at the request of the Assignee, all documents in connection with any application for United States letters patent therefor.

Payment Received. I am making this assignment in consideration of One Dollar and other good and valuable consideration. I acknowledge the receipt and sufficiency of the consideration.

Authorizations. I request the U.S. Commissioner of Patents and Trademarks to issue the Letters Patent to the Assignee. I authorize the attorney(s) of record in the application to insert in this assignment document the date and serial number of the application.

Further Acts. I agree, upon the request and at the expense of the Assignee, to execute any divisional, continuation or substitute application for the invention or improvements, and any oath, declaration or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon the application. I agree to perform, upon request, any affirmative acts to obtain said Letters Patent of the United States and to vest in the Assignee all rights therein, so that the Letters Patent will be held and enjoyed by the Assignee, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me if this assignment had not been made.

Interference. In the event that any application or Letters Patent that I now assign becomes involved in interference, I agree to cooperate to the best of my ability in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof.

Takahiro IBE 09/04/2012
Name: Takahiro IBE Date

Tomoya AOYAMA 09/05/2012
Name: Tomoya AOYAMA Date

Name: Rena TSURUOKA Date

Name: Satoshi INOUE Date

Name: Tohru SONODA

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Tohru Sonoda

09/10/2012

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Date